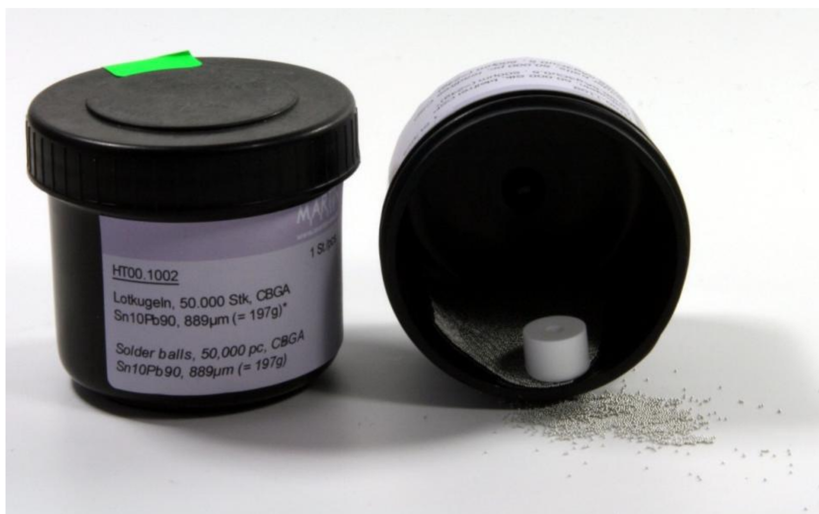
SCHEDA TECNICA

SOLDER BALLS for BGA Reballing



High quality Solder Balls are available directly from MARTIN for reballing using MARTIN's MINIOVEN 04.
MARTIN Solder Balls are packaged under Argon inert gas atmospheres in quantities of up to 50.000 to prevent oxidation and promote a superior reballing process. Oxidation prevents solder alloys from wetting properly during the soldering process, enables voiding and jeopardizes the Rework process.
MARTIN's MINIOVEN 04 is a robust and easy to use dedicated reballing tool with an integrated soldering process controller. A prepared SMD component is loaded into the reballing fixture. The fixture pre-aligns the SMD with a stencil that enables poured Solder Balls to mate with the SMD's interconnecting pads and allows excess Solder Balls to be collected. The SMD and properly aligned Solder Balls housed within the reballing fixture are loaded into the MARTIN MINIOVEN 04 and reflowed under precise control.

Fetaures

All Solder Ball boxes have quantity of 50.000pcs
and are prefilled with dry, inert Argon gas.

Storage life of closed boxes is 12 months,
after opening 6 months.

Technical Data

Lead Free(SnAg3,5Cu0,5)

Size Range:	Ø 0,2–1,0 mm ±0,01 mm
Alloy:	Sn Balance, Ag 3,0–4,0% Cu 0,4–0,6%
Melting Point:	217-220 °C
Density:	7,37 g/cm³

Leaded (SnPb37)

Size Range:	Ø 0,2–1,0 mm ±0,01 mm
Alloy:	Pb Balance, Sn 62,5-63,5
Melting Point:	183 °C
Density:	8,4 g/cm³

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VD90.5004 Solder Balls, 50,000 pc, CSP	Sn63Pb37, 250µm (= 3,5g) 1 piece
VD90.5104 Solder Balls, 50,000 pc, lead free CSP	Sn96.5Ag3Cu0.5 250µm (=3g)
VD90.5005 Solder Balls, 50,000 pc, CSP	Sn63Pb37, 300µm (= 6g)
VD90.5105 Solder Balls, 50,000 pc, lead free CSP	Sn96.5Ag3Cu0.5 300µm (=5.2g)
VD90.5011 Solder Balls, 50,000 pc, CCSP	Sn10Pb90, 300µm (= 7.6g)
VD90.5115 Solder Balls, 50,000 pc, lead free CSP	Sn96.5Ag3Cu0.5 , 350µm (=7.5g)
VD90.5008 Solder Balls, 50,000 pc, CSP	Sn63Pb37, 400µm (= 14g)
VD90.5108 Solder Balls, 50,000 pc, lead free CSP	Sn96.5Ag3Cu0.5 , 400µm (=12.5g)
VD90.5013 Solder Balls, 50,000 pc, CCSP	Sn10Pb90, 400µm (= 18g)
VD90.5010 Solder Balls, 50,000 pc, CSP	Sn63Pb37, 450µm (= 20g)
VD90.5110 Solder Balls, 50,000 pc, lead free CSP	Sn96,.5Ag3Cu0.5 , 450µm (=18g)
VD90.5009 Solder Balls, 50,000 pc, CSP	Sn63Pb37, 500µm (= 27g)
VD90.5109 Solder Balls, 50,000 pc, lead free CSP	Sn96.5Ag3Cu0.5 ,500µm (=24g)
VD90.5006 Solder Balls, 50,000 pc, BGA	Sn63Pb37, 600µm (= 47g)
VD90.5106 Solder Balls, 50,000 pc, lead free BGA	Sn96.5Ag3Cu0.5 , 600µm (=42g)
VD90.5101 Solder Balls, 50,000 pc, lead free BGA	Sn96.5Ag3Cu0.5, 762µm (=86g)
VD90.5001 Solder Balls, 50,000 pc, BGA	Sn63Pb37, 762µm (= 96g)
VD90.5002 Solder Balls, 50,000 pc, CBGA	Sn10Pb90, 889µm (= 197g)